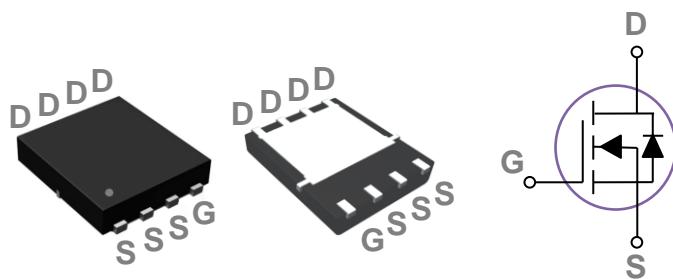


### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### PPAK5X6 Pin Configuration



BVDSS	RDS(ON)	ID
80V	3.5mΩ	130A

### Features

- 80V, 130A,  $RDS(ON) = 3.5m\Omega @ VGS = 10V$
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### Applications

- Networking
- Load Switch
- LED applications
- Quick Charger

### Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	80	V
$V_{GS}$	Gate-Source Voltage	+20/-12	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ C$ )	130	A
	Drain Current – Continuous ( $T_c=100^\circ C$ )	82	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	520	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	400	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	90	A
$P_D$	Power Dissipation ( $T_c=25^\circ C$ )	142	W
	Power Dissipation – Derate above 25°C	1.13	W/°C
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	°C/W
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	0.88	°C/W

**Electrical Characteristics ( $T_J=25\text{ }^{\circ}\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	80	---	---	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=80\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	---	1	$\mu\text{A}$
		$V_{DS}=64\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=85\text{ }^{\circ}\text{C}$	---	---	10	$\mu\text{A}$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=20\text{V}$ , $V_{DS}=0\text{V}$	---	---	100	$\text{nA}$

**On Characteristics**

$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}$ , $I_D=20\text{A}$	---	2.9	3.5	$\text{m}\Omega$
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250\mu\text{A}$	2	3	4	V
$g_{fs}$	Forward Transconductance	$V_{DS}=10\text{V}$ , $I_D=5\text{A}$	---	19	---	S

**Dynamic and switching Characteristics**

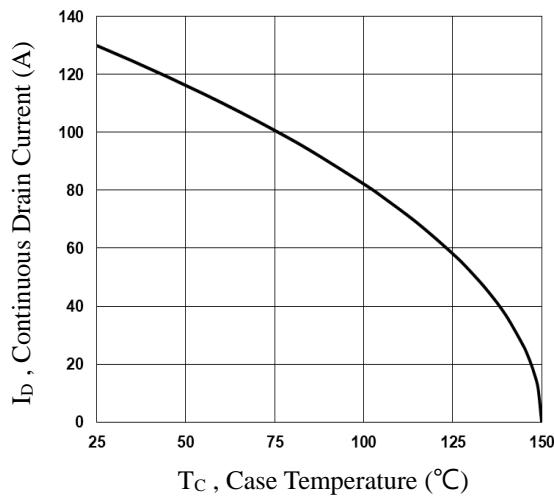
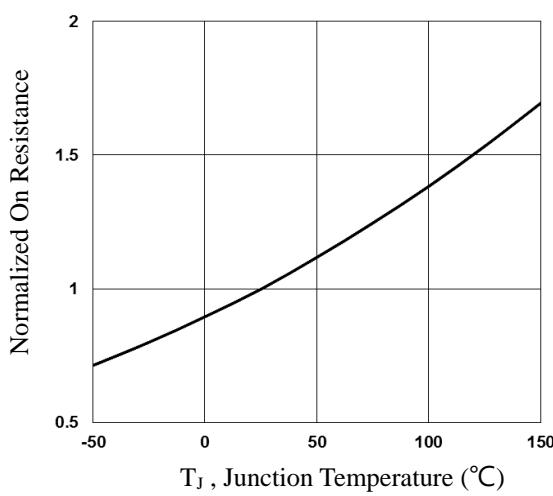
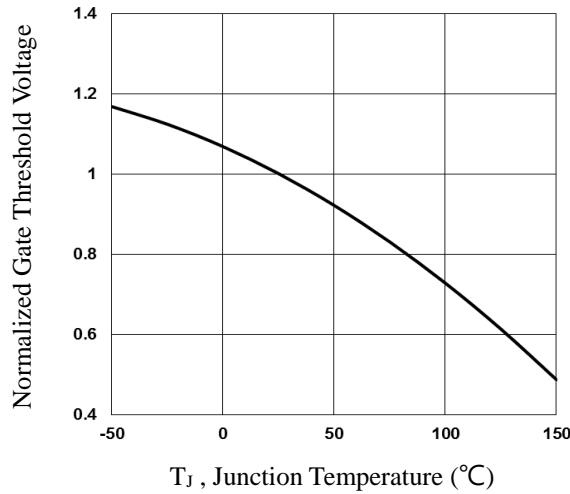
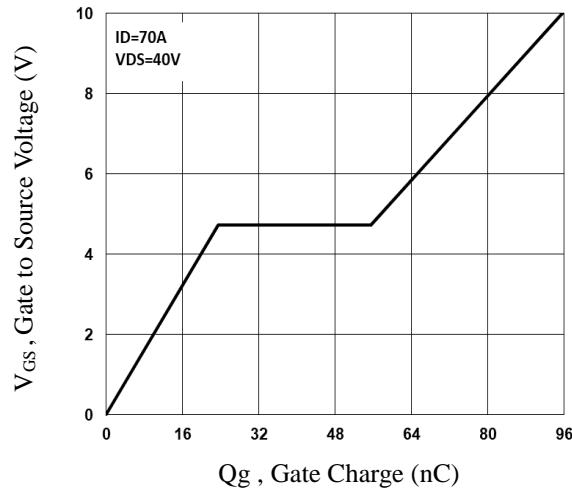
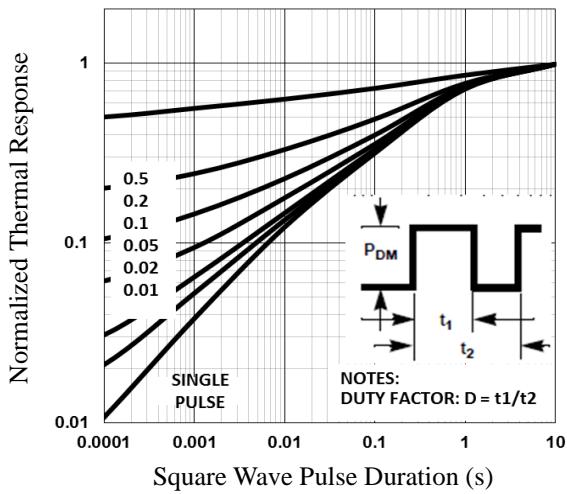
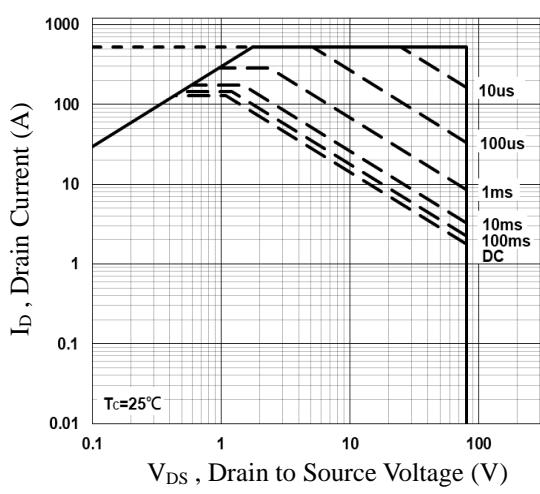
$Q_g$	Total Gate Charge <sup>3, 4</sup>	$V_{DS}=40\text{V}$ , $V_{GS}=10\text{V}$ , $I_D=70\text{A}$	---	95.5	143	nC
$Q_{gs}$	Gate-Source Charge <sup>3, 4</sup>		---	23.5	35	
$Q_{gd}$	Gate-Drain Charge <sup>3, 4</sup>		---	32	48	
$T_{d(on)}$	Turn-On Delay Time <sup>3, 4</sup>	$V_{DD}=40\text{V}$ , $V_{GS}=10\text{V}$ , $R_G=6\Omega$ $I_D=70\text{A}$	---	22	33	ns
$T_r$	Rise Time <sup>3, 4</sup>		---	15	23	
$T_{d(off)}$	Turn-Off Delay Time <sup>3, 4</sup>		---	40	60	
$T_f$	Fall Time <sup>3, 4</sup>		---	19	29	
$C_{iss}$	Input Capacitance	$V_{DS}=40\text{V}$ , $V_{GS}=0\text{V}$ , $F=1\text{MHz}$	---	5510	8265	pF
$C_{oss}$	Output Capacitance		---	1200	1800	
$C_{rss}$	Reverse Transfer Capacitance		---	70	100	
$R_g$	Gate resistance	$V_{GS}=0\text{V}$ , $V_{DS}=0\text{V}$ , $F=1\text{MHz}$	---	1.5	---	$\Omega$

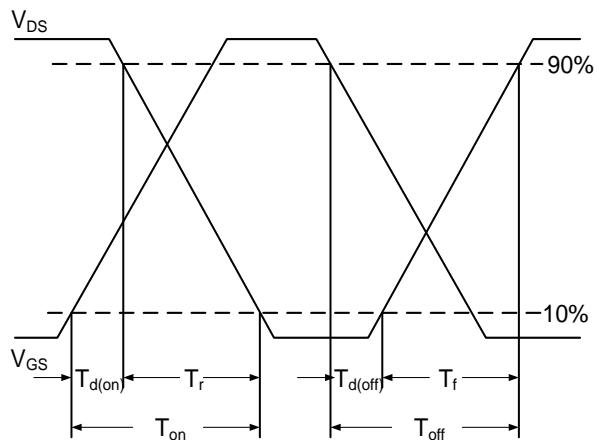
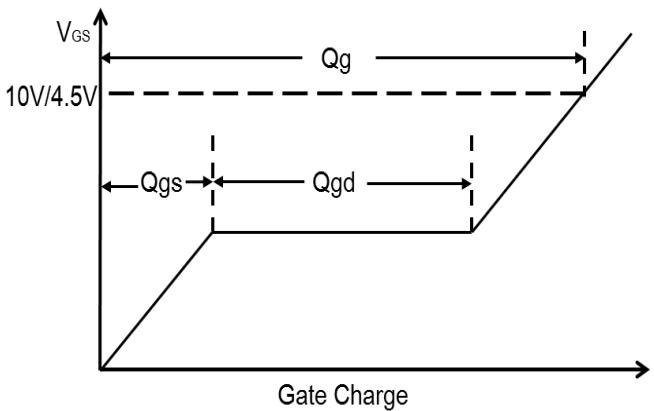
**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	130	A
$I_{SM}$	Pulsed Source Current		---	---	260	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	---	1	V
$t_{rr}$	Reverse Recovery Time	$V_R=50\text{V}$ , $I_s=10\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	65	---	nS
$Q_{rr}$	Reverse Recovery Charge		---	130	---	nC

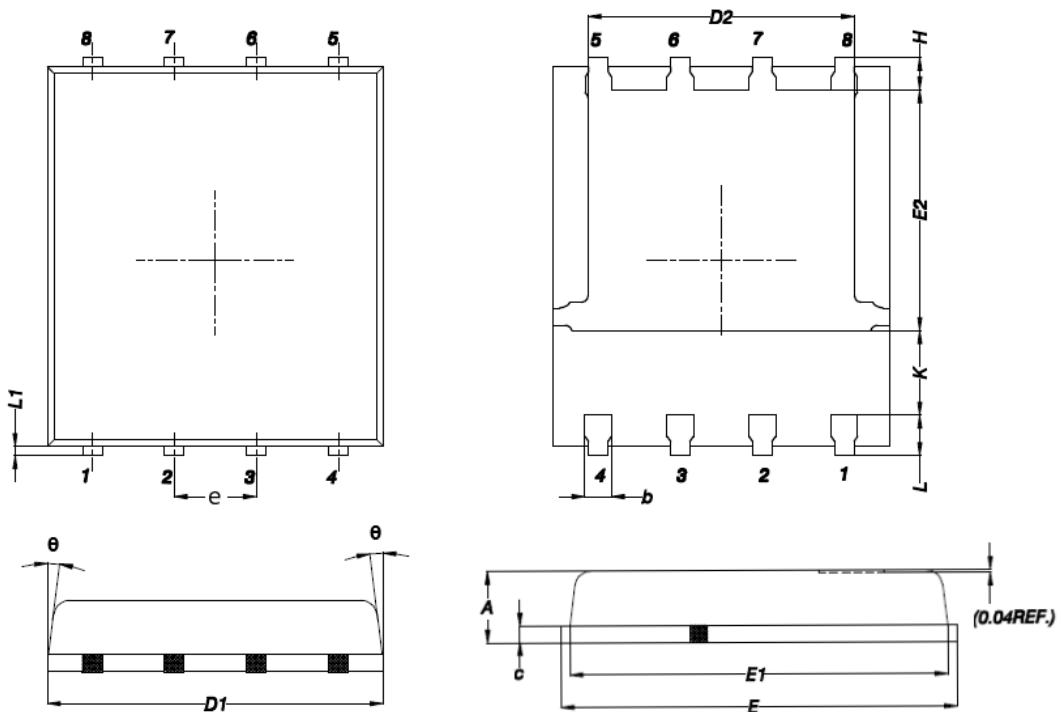
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=25\text{V}$ ,  $V_{GS}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{AS}=90\text{A}$ ,  $R_G=25\Omega$ , Starting  $T_J=25\text{ }^{\circ}\text{C}$ .
3. The data tested by pulsed, pulse width  $\leq 300\text{us}$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.


**Fig.1 Continuous Drain Current vs. T<sub>c</sub>**

**Fig.2 Normalized R<sub>DS(on)</sub> vs. T<sub>j</sub>**

**Fig.3 Normalized V<sub>th</sub> vs. T<sub>j</sub>**

**Fig.4 Gate Charge Characteristics**

**Fig.5 Normalized Transient Impedance**

**Fig.6 Maximum Safe Operation Area**


**Fig.7 Switching Time Waveform**

**Fig.8 Gate Charge Waveform**

## PPAK5x6 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.200	0.850	0.047	0.031
b	0.510	0.300	0.020	0.012
C	0.300	0.200	0.012	0.008
D1	5.400	4.800	0.212	0.189
D2	4.310	3.610	0.170	0.142
E	6.300	5.850	0.248	0.230
E1	5.960	5.450	0.235	0.215
E2	3.920	3.300	0.154	0.130
e	1.27BSC		0.05BSC	
H	0.650	0.380	0.026	0.015
K	---	1.100	---	0.043
L	0.710	0.380	0.028	0.015
L1	0.250	0.050	0.009	0.002
θ	12°	0°	12°	0°